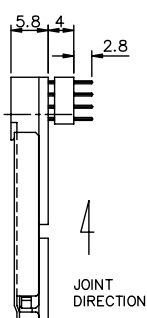
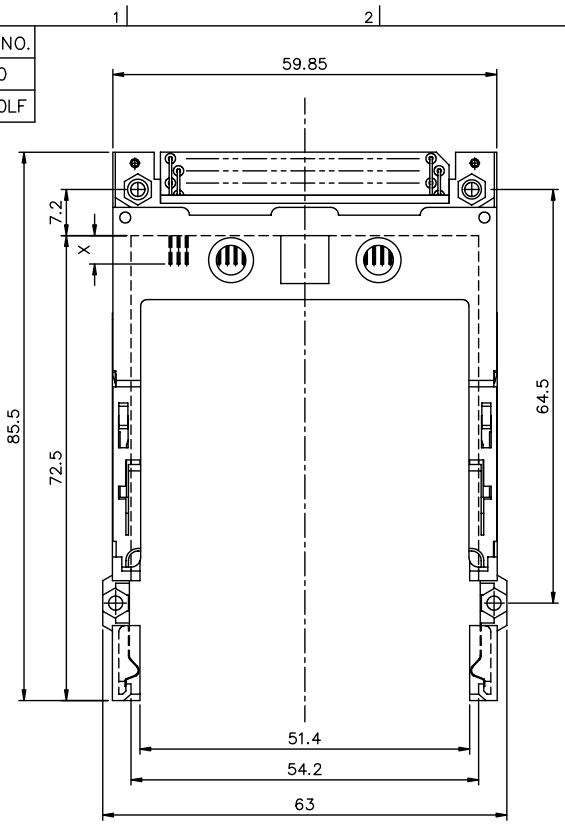


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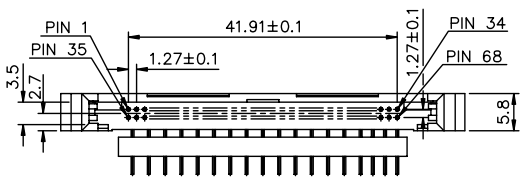
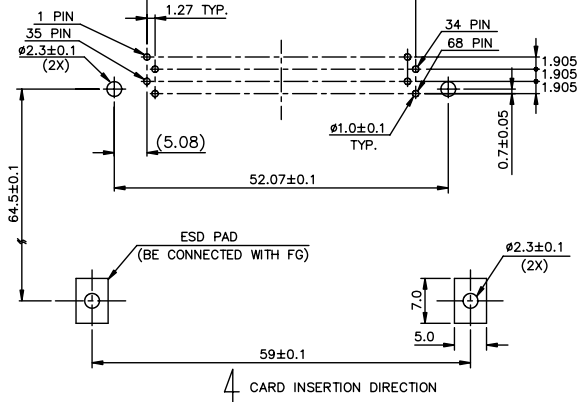
PRODUCT NO.
74500-040
74500-040LF



- NOTES:
- EJECT FORCE : 3.5 Kg MAX.
 - EJECT TRAVEL: 8.0mm
 - MATERIAL
 - HEADER ASS'Y :
 PLASTIC : HOUSING ...LCP UL94V-0 BLACK
 PIN : PHOSPHOR BRONZE
 - EJECT MECHANISM ASS'Y :
 PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK
 PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK
 PLATE : STAINLESS
 EMI CONTACT: PHOSPHOR BRONZE
 - FINISH (PIN)
 UNDER PLATING : 0.5µm MIN. Ni
 CONTACT AREA : 0.1µm MIN. GOLD OVER
 0.5µm MIN. Pd-Ni
 SOLDER TAIL : 2.5µm MIN. Sn-Pb (FOR TIN LEAD OPTION)
 : 2.5µm MIN. PURE TIN (FOR LEAD FREE OPTION)

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68	

- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION 41.91±0.1



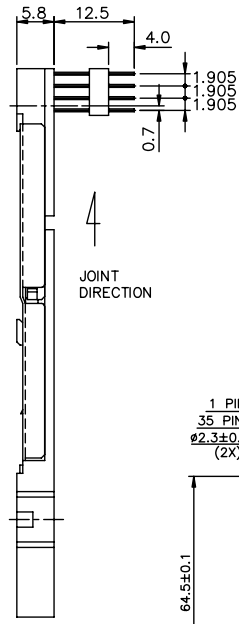
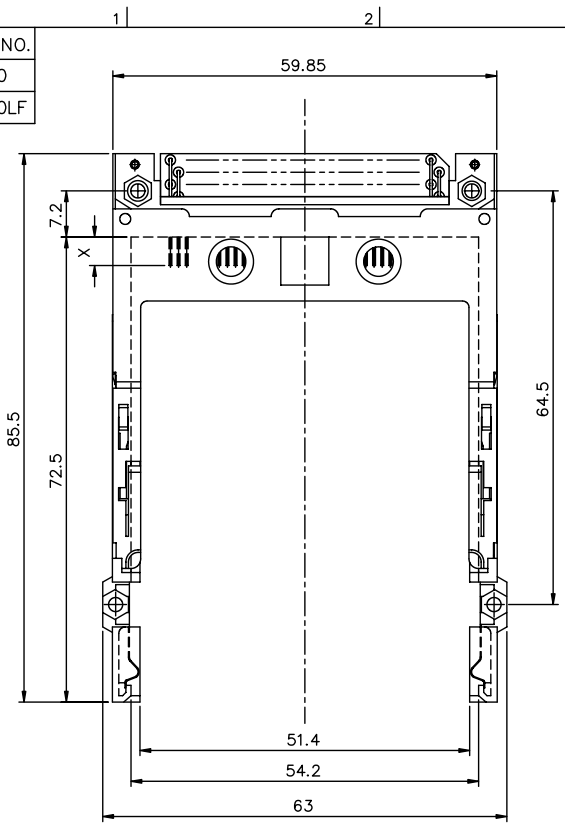
mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
rev.	ecn no.	dr	date	linear	±0.30	projection	title
A	T70405	W	08/23/97				EJECTOR HEADER ASS'Y
B	T80096	W	02/17/98				68POS. R/A TYP 1/2/3
C	T03-0328	W	08/14/03	angles	± 2°		
D	N05-0127	W	05/11/05	dr	WENDY CHEN 07/30/97	unit	product family
				engr	JOSEPH HSIA 07/30/97	mm/inch	PCBGA
				chr	JOSEPH HSIA 07/30/97	scale	size
				appd	JENN TSAO 07/30/97	1.6:1	dwg no.
sheet	revision	D	D				74500
index	sheet	1	2				code
							1 OF 2

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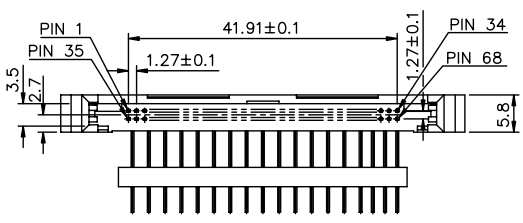
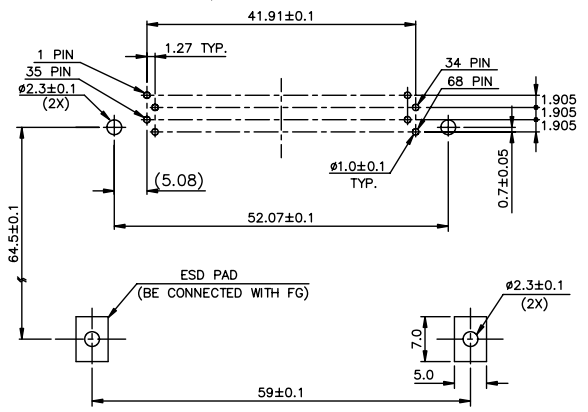
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PRODUCT NO.
74500-000
74500-000LF



- NOTES:
- MATERIAL
 - HEADER ASS'Y :
 PLASTIC : HOUSING : LCP UL94V-0 BLACK
 PIN : PHOSPHOR BRONZE
 - EJECT MECHANISM ASS'Y :
 PLASTIC : GUIDE : POLYPHTHARAMID UL94V-0 BLACK
 PLATE : STAINLESS
 EMI CONTACT : PHOSPHOR BRONZE
 - FINISH (PIN)
 UNDER PLATING : 0.5µm MIN. Ni
 CONTACT AREA : 0.1µm MIN. GOLD OVER
 0.5µm MIN. Pd-Ni
 SOLDER TAIL : 2.5µm MIN. Sn-Pb (FOR TIN LEAD OPTION)
 : 2.5µm MIN. PURE TIN (FOR LEAD FREE OPTION)
 - DIM "X"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
 - IF LEAD FREE P.N. THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 - IF LEAD FREE P.N. THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
 - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



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rev.	ecn no.	dr	date	linear	± 0.30	projection	title			
D				angles	± 2°		EJECTOR HEADER ASS'Y			
				dr	WENDY CHEN 02/17/98	unit	product family		pack	code
				engr	JOSEPH HSIA 02/17/98	mm/inch	68POS. R/A TYP 1/2/3			
				chr	JOSEPH HSIA 02/17/98	scale	size		dwg no.	sheet
				appd	JENN TSAO 02/17/98	1.6:1	A3		74500	2 of
sheet	revision									
index	sheet									

PDM: Rev:D STATUS: Released Printed: Oct 12, 2010